

## Vertical Type 2-Chamber Oven



### Cure and Inert Oven, 2-chamber type

Cure for BGA/CSP (PBGA/CABG/LFBGA/SBGA/TABGA/FilipChip) manufacturing process.

- Expandable and detachable
- Can select number of ovens
- Saving space in factory
- Easy maintenance
- Oxygen exchange rate is under 100 ppm level for Inert
- Cooling Time (175C to 50C) - less than 30min for Inert



Method : Forced convection  
 Temp. range : 40 to 260 deg.C  
 Temp. uniformity :  $\pm 3$ deg.C with sample Loading  
 Internal dimension : W580 x D615 x H580

Other :  
 Auto damper with Exhaust duct  
 N2 gas inlet port  
 Solenoid door lock  
 Level adjustable shelf  
 Program security function



Cooling coil system for Inert



Chamber



Back View